

Final Product/Process Change Notification Document #:FPCN25572Z20 Issue Date: 05 Feb 2024

Title of Change:	Update to FPCN25572Z - To include the reliability data of 3V Minigates SC88A for the qualification of Vanguard Fab and Assembly Related Changes for Logic part.
Proposed Changed Material First Ship Date:	12 Aug 2024 or earlier if approved by customer
Current Material Last Order Date:	20 Nov 2023 Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.
Current Material Last Delivery Date:	N/A The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory
Product Category:	Active components – Integrated circuits
Contact information:	Contact your local onsemi Sales Office or logic.fpcn@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Sample Availability Date:	19 Jan 2024
PPAP Availability Date:	26 Feb 2024
Additional Reliability Data:	Contact your local onsemi Sales Office or ChangKit.Mok@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact <u>PCN.Support@onsemi.com</u> .
Change Category	
Category	Type of Change
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor, New wafer diameter
Equipment	Production from a new equipment/tool which uses a different basic technology or which due to its unique form or function can be expected to influence the integrity of the final product
Data Sheet	Change of datasheet parameters/electrical specification (min./max./typ. values) and/or AC/DC specification
Process - Assembly	Change of wire bonding

Description and Purpose:

With reference to **FPCN25572Z**, this FPCN presents the information solely for 3V Minigates in SC88A package.

	From	То
Fab Site	Tower	Vanguard
Wafer Diameter	6 inch	8 inch
Bond Wire	Au	Cu

Onsemi

Final Product/Process Change Notification Document #:FPCN25572Z20 Issue Date: 05 Feb 2024

3V Minigates Datasheet Updates:

NLV17SGxx to NL17SGxx-Q Family

NLV17SG except for NLV17SGU04 – Max Ratings

New

Existing

ymbol		Parameter	Value	Unit
Vcc	DC Supply Voltage		-0.5 to +5.5	V
VIN	DC Input Voltage		-0.5 to +4.6	V
Vout	DC Output Voltage	Output at High or Low State Power-Down Mode (V _{CC} = 0 V)	-0.5 to V _{CC} +0.5 -0.5 to +4.6	V
IIK	DC Input Diode Current	V _{IN} < GND	-20	mA
lok	DC Output Diode Current	V _{OUT} < GND	-20	mA
IOUT	DC Output Source/Sink Current		±20	mA
lcc	DC Supply Current per Supply Pin		±20	mA
IGND	DC Ground Current per Ground Pin		±20	mA
TSTG	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case	for 10 Seconds	260	°C
TJ	Junction Temperature Under Bias		+150	°C
MSL	Moisture Sensitivity		Level 1	
FR	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
VESD	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3)	>2000 >100	V
ATCHUP	Latchup Performance	Above V _{CC} and Below GND at 125°C (Note 4)	±100	mA

Symbol	Parameter		Value	Uni
Voc	DC Supply Voltage		-0.5 to +4.3	V
VIN	DC Input Voltage		-0.5 to +4.3	V
VOUT	Tri-S	High or Low State) tate Mode (Note 1) Mode (V _{CC} = 0 V)	-0.5 to V _{CC} + 0.5 -0.5 to +4.3 -0.5 to +4.3	v
IIK	DC Input Diode Current	V _{IN} < GND	-20	mA
IOK	DC Output Diode Current	V _{OUT} < GND	-20	mA
lout	DC Output Source/Sink Current		±20	mA
CC or IGND	DC Supply Current Per Supply Pin or Ground Pin		±20	mA
TSTG	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
TJ	Junction Temperature Under Bias		+150	°C
θ _{JA}	Thermal Resistance (Note 2)	SC-88A SOT-953 UDFN6	377 254 154	°C/V
PD	Power Dissipation in Still Air at 85°C	SC-88A SOT-953 UDFN6	332 491 812	mV
MSL	Moisture Sensitivity		Level 1	
FR	Flammability Rating Oxyg	gen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
VESD		luman Body Model rged Device Model	2000 1000	V
LATCHUP	Latchup Performance (Note 4)		±100	mA

CTERISTICS

1.1 to 1.3 1.4 to 1.6 1.65 to 1.95 0.65 x V_{CC} 0.65 x V_{CC}

3.0 to 3.6 2.0

1.1 to 1.3 1.4 to 1.6

1.65 to 1.9

2.3 to 2.7

3.0 to 3.6 0.9

1.4 to 1.6 1.65 to 1.95

0.9 1.1 to 1.3 1.4 to 1.6 l_{OL} = 0.3 mA l_{OL} = 1.7 mA

0

0.9 to 3.6

I_{OL} = 3.0 mA 1.65 to 1.95 I_{OL} = 4.0 mA 2.3 to 2.7 I_{OL} = 8.0 mA 2.7 to 3.6 0 V to 3.6 V 0.9 to 3.6

H = -0.3 m 1.1 to 1.3

> -1.7 mA = -8.0 mA 3.0 to 3.6

1.7

.75 x Vo

2.48

All NLV17SG except for NLV17SG07/14/17/U04 - DC **Characteristics** New Existing

					T _A =	25°C		+125°C			Table 3.	DC ELECTRICA	L CHARACT
Symbol	Parameter	с	onditions	Vcc (V)	Min	Max	Min	Max	Unit		Symbol		-
IH	High-Level Input			0.9	Vcc		Vcc		Y	1	V	High-Level Input	
1	Voltage			1.1 to 1.3	0.7xV _{CC}		0.7xV _{CC}					Voltage	
				1.4 to 1.6	0.65xV _{CC}		0.65xV _{CC}		1	N	1		
				1.65 to 1.95	0.65xV _{CC}		0.65xV _{CC}		1				
				2.3 to 2.7	1.7		1.7						
				3.0 to 3.6	2.0		2.0		1				-
VIL	Low-Level Input			0.9		GND		GND	V	1	V _R	Low-Level Input Voltage	
	Voltage			1.1 to 1.3		0.3xVcc		0.3xVcc	1				
				1.4 to 1.6		0.35xV _{CC}		0.35xV _{CC}					
				1.65 to 1.95		0.35xVoc		0.35xVcc	1				
				2.3 to 2.7		0.7		0.7					
				3.0 to 3.6		0.8	-	0.8			VOH	High-Level Output Voltage	VIN = VIH or
VOH	High-Level	V _{IN} =	I _{OH} = -20 μA	0.9	0.75		0.75		V			Voltage	IOH =
	Output Voltage	V _{IH} or V _{IL}	I _{OH} = -0.3 mA	1.1 to 1.3	0.75xVcc		0.75xVcc		1				I _{OH} = -
			I _{OH} = -1.7 mA	1.4 to 1.6	0.75xV _{CC}		0.75xVcc		1				IOH = -
			I _{OH} = -3.0 mA	1.65 to 1.95	X-01			I _{OH} = -					
													I _{OH} = -
			I _{OH} = -4.0 mA	2.3 to 2.7	2.0		2.0				VoL	Low-Level Outpu	
			I _{OH} = -8.0 mA	3.0 to 3.6	2.48		2.48				1.00	Voltage	loL
VOL	Low-Level Output Voltage	V _{IN} = V _{IN} or	I _{OL} = 20 μA	0.9		0.1		0.1	V				lot =
	Output voltage	V _{IH} or V _{IL}	I _{OL} = 0.3 mA	1.1 to 1.3		0.25xV _{CC}		0.25xV _{CC}					IOL =
			I _{OL} = 1.7 mA	1.4 to 1.6		0.25xVoc		0.25xVcc					IOL =
			I _{OL} = 3.0 mA	1.65 to 1.95		0.45		0.45					I _{OL} =
			l _{OL} = 4.0 mA	2.3 to 2.7		0.4		0.4					IOL =
			I _{OL} = 8.0 mA	3.0 to 3.6		0.4		0.4			In	Input Leakage Current	V _{IN} = 0 V to
IIN	Input Leakage Current		V _{IN} ≤ 3.6 V	0 to 3.6		±0.1		± 1.0	μΑ		lorr	Power Off Leakage Current	V _{IN} = 0 V to V _{OUT} = 0 V
loc	Quiescent Supply Current	V _{IN} =	Vcc or GND	3.6		0.5		10.0	μΑ		1cc	Quiescent Supply Current	VIN = VCC

T_A = -55°C to +125°C

0.35 x \

0.65 × V_{CC} 0.65 × V_{CC}

0.75 x V_{CC}

0.75 x V_{CC}

2.48

0.35 x V

0.35 x V_{CC}

0.7

0.25 x V_{CC}

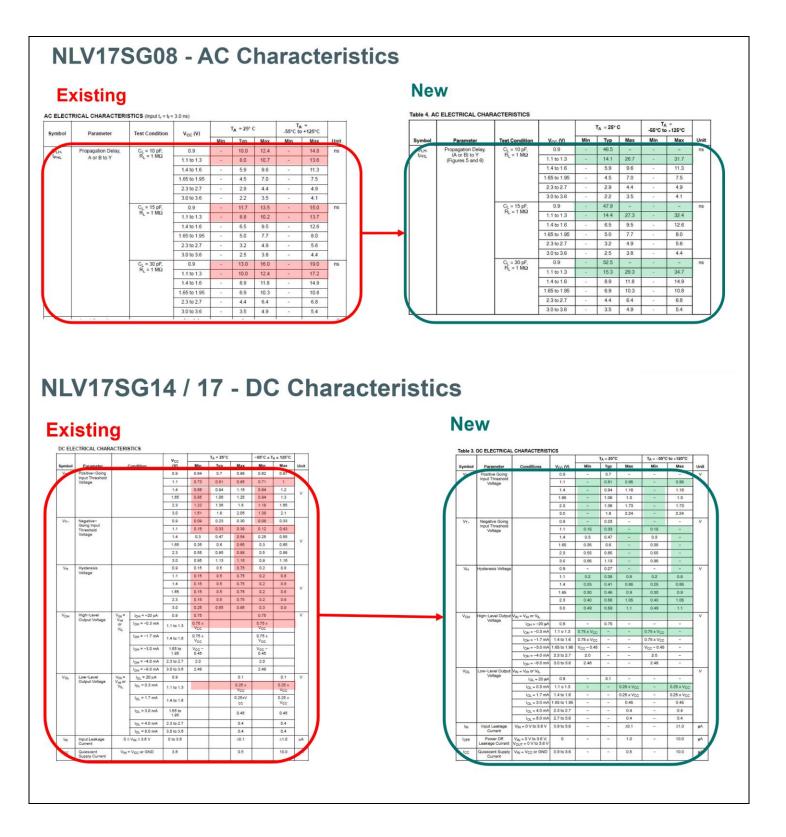
0.45 0.4

±0.1

1.0

TA = 25

Final Product/Process Change Notification Document #:FPCN25572Z20 Issue Date: 05 Feb 2024



Final Product/Process Change Notification Document #:FPCN25572Z20 Issue Date: 05 Feb 2024

NLV17SG14 - AC Characteristics

Existing

				T _A = 25 °C				= +125°C	
ymbol	Parameter	Test Condition	Vac (V)	Min	Typ	Max	Min	Max	Unit
PLH- tPHL	Propagation Delay, A or Y	C _L = 10 pF.	0.9	-	27.3	-	-	-	ns
PHL	A or Y	$R_L = 1 M\Omega$	1.1 to 1.3	-	13.0	22.6	1.0	35.9	1
			1.4 to 1.6	-	7.5	10.5	1.0	11.3	1
			1.65 to 1.95	-	6.0	7.8	1.0	8.2	1
			2.3 to 2.7	-	4.3	5.4	1.0	5.8	1
			3.0 to 3.6	-	3.5	4.4	1.0	4.6	1
		CL = 15 pF.	0.9	-	29.5		-		ns
		$R_L = 1 M\Omega$	1.1 to 1.3	-	14.3	25.1	1.0	41.6	1
			1.4 to 1.6	-	8.0	11.5	1.0	12.6	1
			1.65 to 1.95	-	6.3	8.4	1.0	8.7	
			2.3 to 2.7	-	4.6	5.7	1.0	6.1	
			3.0 to 3.6		3.7	4.6	1.0	5.0	
		CL = 30 pF.	0.9	-	40.5		-	2. . .	ns
		$R_L = 1 M\Omega$	1.1 to 1.3	-	19.6	35.7	1.0	58.1	1
			1.4 to 1.6	-	10.7	15.8	1.0	17.6	1
			1.65 to 1.95	-	7.8	10.7	1.0	11.7	1
			2.3 to 2.7	-	5.4	0.9	1.0	8.1	1
			3.0 to 3.6	-	4.3	5.2	1.0	6.1	1

				T _A = 25°C		;		+125°C	
Symbol	Parameter	Test Condition	Vcc (V)	Min	Тур	Max	Min	Max	Unit
PLH- TPHL	Propagation Delay,	CL = 10 pF,	0.9	-	38.0	-	-	-	n.
TPHL	A to Y (Figures 5 and 6)	$R_L = 1 M\Omega$	1.1 to 1.3	-	9.7	24.1	-	35.9	
	(rightes o and o)		1.4 to 1.6	-	5.4	10.5	-	11.3	
			1.65 to 1.95	-	3.9	7.8	-	8.2	
			2.3 to 2.7	-	2.8	5.4	-	5.8	
			3.0 to 3.6	-	2.3	4.4	-	4.6	
		$\begin{array}{l} C_L = 15 \ \text{pF}, \\ R_L = 1 \ \text{M}\Omega \end{array}$	0.9	-	38.4	-	-	-	
	,		1.1 to 1.3	-	9.9	25.1	-	41.6	
			1.4 to 1.6	-	5.6	11.5	-	12.6	
			1.65 to 1.95	-	4.1	8.4	-	8.7	
			2.3 to 2.7	-	2.9	5.7	-	6.1	
			3.0 to 3.6	-	2.4	4.6	-	5.0	
		C _L = 30 pF,	0.9	-	39.6	-	-	-	
		$R_L = 1 M\Omega$	1.1 to 1.3	-	10.5	35.7	-	58.1	
			1.4 to 1.6	-	6.0	15.8	-	17.6	
			1.65 to 1.95	-	4.7	10.7	-	11.7	
			2.3 to 2.7	-	3.2	6.9	-	8.1	
			3.0 to 3.6	-	2.6	5.2	-	6.1	

NLV17SGU04 – Max Ratings

Existing

symbol	Param	ieter	Value	Unit
Vcc	DC Supply Voltage		-0.5 to +4.6	V
VIN	DC Input Voltage		-0.5 to +4.6	V
Vout	DC Output Voltage	Output at High or Low State Power-Down Mode (V _{CC} = 0 V)	-0.5 to V _{CC} +0.5 -0.5 to +4.6	V
IIK	DC Input Diode Current	V _{IN} < GND	-20	mA
lok	DC Output Diode Current	V _{OUT} < GND	-20	mA
lout	DC Output Source/Sink Current		±20	mA
lcc	DC Supply Current per Supply Pin		±20	mA
IGND	DC Ground Current per Ground Pin		±20	mA
TSTG	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 S	Seconds	260	°C
TJ	Junction Temperature Under Bias		+150	°C
MSL	Moisture Sensitivity		Level 1	Ű.
FR	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	j.
V _{ESD}	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3)	>2000 >150	V
ATCHUP	Latchup Performance Abo	ve V _{CC} and Below GND at 125°C (Note 4)	±100	mA

New

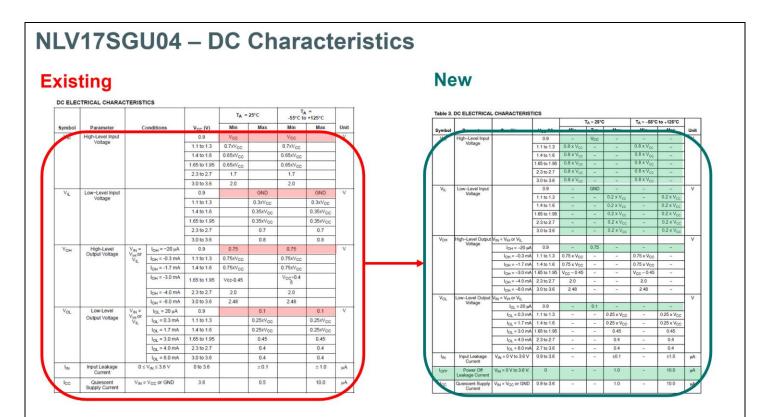
New

Symbol	Parameter		Value	Unit
Vcc	DC Supply Voltage		-0.5 to +4.3	V
VIN	DC Input Voltage		-0.5 to +4.3	V
VOUT	DC Output Voltage		-0.5 to V _{CC} + 0.5	V
I _{IK}	DC Input Diode Current	V _{IN} < GND	-20	mA
lok	DC Output Diode Current		±20	mA
lour	DC Output Source/Sink Current		±20	mA
CC or IGND	DC Supply Current Per Supply Pin or Ground Pin		±20	mA
TSTG	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
TJ	Junction Temperature Under Bias		+150	°C
θ _{JA}	Thermal Resistance (Note 2)	SC-88A SOT-953 UDFN6	377 254 154	°C/W
PD	Power Dissipation in Still Air at 85°C	SC-88A SOT-953 UDFN6	332 491 812	mW
MSL	Moisture Sensitivity		Level 1	
FR	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
VESD	ESD Withstand Voltage (Note 3)	Human Body Model Charged Device Model	2000 1000	V
LATCHUP	Latchup Performance (Note 4)		±100	mA

Symbol	Charact	eristics	Min	Max	Unit
Vcc	Positive DC Supply Voltage		0.9	3.6	V
VIN	Digital Input Voltage		0.0	3.6	V
VOUT	Output Voltage	Output at High or Low State Power-Down Mode (V _{CC} = 0 V)	0.0 0.0	V _{CC} 3.6	V
TA	Operating Temperature Range		-55	+125	°C
At / AV	Input Transition Rise or Fail Rate	V _{CC} = 3.3 V ± 0.3 V	0	10	ns/V

Symbol	Characteristics	Min	Max	Uni
Vcc	Positive DC Supply Voltage	0.9	3.6	V
VIN	Digital Input Voltage	0.0	3.6	V
VOUT	Output Voltage	0.0	Vcc	V
TA	Operating Temperature Range	-55	+125	°C
Δt / ΔV	Input Transition Rise or Fail Rate V _{CC} = 3.	3 V ± 0.3 V 0	10	ns/\

Final Product/Process Change Notification Document #:FPCN25572Z20 Issue Date: 05 Feb 2024



NLV17SGU04 - AC Characteristics

Existing

symbol	Parameter	Test Condition	V _{cc} (V)		T _A = 25° (:		+125°C	
				Min	Тур	Max	Min	Max	Unit
PLH.	Propagation Delay,	C _L = 10 pF,	0.9	-	8.0	10.3		13.3	ns
IPHL	A to Y	$R_L = 1 M\Omega$	1.1 to 1.3		6.0	9.4	-	12.2	1
			1.4 to 1.6		3.2	8.5	0	10.0	1
			1.65 to 1.95		2.6	6.2		6.7	1
			2.3 to 2.7		2.0	3.9		4.4	1
			3.0 to 3.6		1.7	3.1	-	3.7	1
		C _L = 15 pF, R _L = 1 MΩ	0.9	-	19.5	11.7		14.5	ns
			1.1 to 1.3		7.0	9.2		12.2	
			1.4 to 1.6		3.5	6.3	-	10.2	
			1.65 to 1.95		3.0	5.9		7.1	
			2.3 to 2.7		2.3	4.4	-	5.0	
			3.0 to 3.6		1.9	3.4		3.9	1
		C _L = 30 pF,	0.9	-	10.0	12.5		15.6	ns
		$R_L = 1 M\Omega$	1.1 to 1.3	-	9.0	11.6		13.8	1
			1.4 to 1.6		6.0	9.1	1.0	12.9	1
			1.65 to 1.95		4.5	8.2		9.6	1
			2.3 to 2.7	-	3.2	5.7	-	6.1	1
			3.0 to 3.6		2.5	4.4	-	4.8	1

New

Symbol	Parameter	Test Condition	V _{cc} (V)	T _A = 25° C		T _A = -55°C to +125°C			
				Min	Тур	Max	Min	Max	Unit
tрнL	Propagation Delay, A to Y C _L = 10 pF, R _L = 1 MΩ C _L = 15 pF, R _L = 1 MΩ C _L = 1 MΩ	C _L = 10 pF, R _L = 1 MΩ	0.9	-	12.7	-	•		
			1.1 to 1.3	-	6.0	9.2	-	12.2	
			1.4 to 1.6	-	3.2	8.5		10.0	1
			1.65 to 1.95	-	2.6	6.2	-	6.7	1
			2.3 to 2.7	-	2.0	3.9	-	4.4	-
			3.0 to 3.6	-	1.7	3.1	-	3.7	
		C _L = 15 pF,	0.9	-	13.0	•	-	-	ns
		$R_L = 1 M\Omega$	1.1 to 1.3	-	7.0	9.4	-	12.2	
			1.4 to 1.6	-	3.5	6.3	-	10.2	
			1.65 to 1.95	-	3.0	5.9	-	7.1	
			2.3 to 2.7	-	2.3	4.4	-	5.0	
			3.0 to 3.6	-	1.9	3.4	-	3.9	
		C _L = 30 pF,	0.9	-	14.1	-	-	-	ns
		1.1 to 1.3	-	9.0	11.6	-	13.8	1	
			1.4 to 1.6	-	6.0	9.1	-	12.9	1
			1.65 to 1.95	-	4.5	8.2	-	9.6	-
			2.3 to 2.7	-	3.2	5.7	-	6.1	
			3.0 to 3.6	-	2.5	4.4		4.8	1

Reason / Motivation for Change:	Supply disruption		
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.		

Sites Affected:				
onsemi Sites		External Foundry/Subcon Sites		
onsemi Leshan, China		Vanguard International Semiconductor, Taiwan		
Marking of Parts/ Traceability of Change:	Custom source on label will show TW instead of US to indicate new die source from Vanguard. Chang material may be identified by plant code or lot code too.			

Reliability Data Summary:

QV DEVICE NAME: NC7SP14P5X RMS: S88008 / S88413 PACKAGE: SC88A

Test	Specification	Condition	Interval	Results
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hours	0/231
Earlier Life Failure Rate	JESD22-A108	Ta=125°C, 100 % max rated Vcc	48 hours	0/2400
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hours	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260°C, Pre TC, uHAST, HAST for surface mount pkgs only	-	0/693
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cycles	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hours	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hours	0/231
Resistance to Solder Heat	JESD22- B106	Ta = 265°C, 10 sec	-	0/30

Note: AEC-1pager is attached.

To view attachments:

1. Download pdf copy of the PCN to your computer

2. Open the downloaded pdf copy of the PCN

3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field

4. Then click on the attached file.

Electrical Characteristics Summary:

Electrical characteristics available upon request.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

Current Part Number	New Part Number	Qualification Vehicle
NLV17SG14DFT2G	NL17SG14DFT2G-Q	NC7SP14P5X
NLV17SG08DFT2G	NL17SG08DFT2G-Q	NC7SP14P5X
NLV17SGU04DFT2G	NL17SGU04DFT2G-Q	NC7SP14P5X